

CMD25N20-VB Datasheet N-Channel 200 V (D-S) MOSFET

PRODUCT	SUMMARY	
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A)
200	0.055 at V _{Cs} = 10 V	30

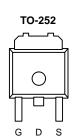
FEATURES

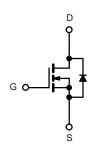
- Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

· Primary Side Switch





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $(T_A = 1)$	25 °C, unless othe	rwise noted)		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	200	V	
Gate-Source Voltage	V _{GS}	± 20	V	
Continuous Drain Current (T _{.I} = 175 °C) ^b	T _C = 25 °C		30	
Continuous Drain Current (1 _J = 175 °C) ²	T _C = 125 °C	I _D	25	
Pulsed Drain Current	I _{DM}	160	А	
Continuous Source Current (Diode Conduction)	I _S	28		
Avalanche Current		I _{AS}	3	
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	18	mJ
Mayimum Dayor Dissination	T _C = 25 °C	P _D	96 ^b	W
Maximum Power Dissipation	T _A = 25 °C		3 ^a	VV
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
lunation to Ambiant	t ≤ 10 s	R _{thJA}	15	18	°C/W		
Junction-to-Ambient ^a	Steady State		40	50			
Junction-to-Case (Drain)		R _{thJC}	0.85	1.1			

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 200 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I_{DSS}	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C			50) μΑ	
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			Α	
		$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.055			
Drain Causes On Chata Decistance	R	V _{GS} = 10 V, I _D = 3 A, T _J = 125 °C		0.060		0	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 3 A, T _J = 175 °C		0.070		Ω	
		V _{GS} = 6 V, I _D = 3 A		0.092			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 3 A		35		S	
Dynamic ^a							
Input Capacitance	C _{iss}			1800		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		180			
Reverse Transfer Capacitance	C _{rss}			80			
Total Gate Charge ^c	Qg			34	51		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3 \text{ A}$		8		nC	
Gate-Drain Charge ^c	Q_{gd}			12			
Gate Resistance	R_g		0.5		2.9	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_{L} = 5.2 \Omega$		50	75	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	115	
Fall Time ^c	t _f			60	90		
Source-Drain Diode Ratings and Char	acteristics (7	T _C = 25 °C)					
Pulsed Current	I _{SM}				5	А	
Diode Forward Voltage ^b	V _{SD}	I _F = 3 A, V _{GS} = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3 A, dI/dt = 100 A/μs		180	250	ns	

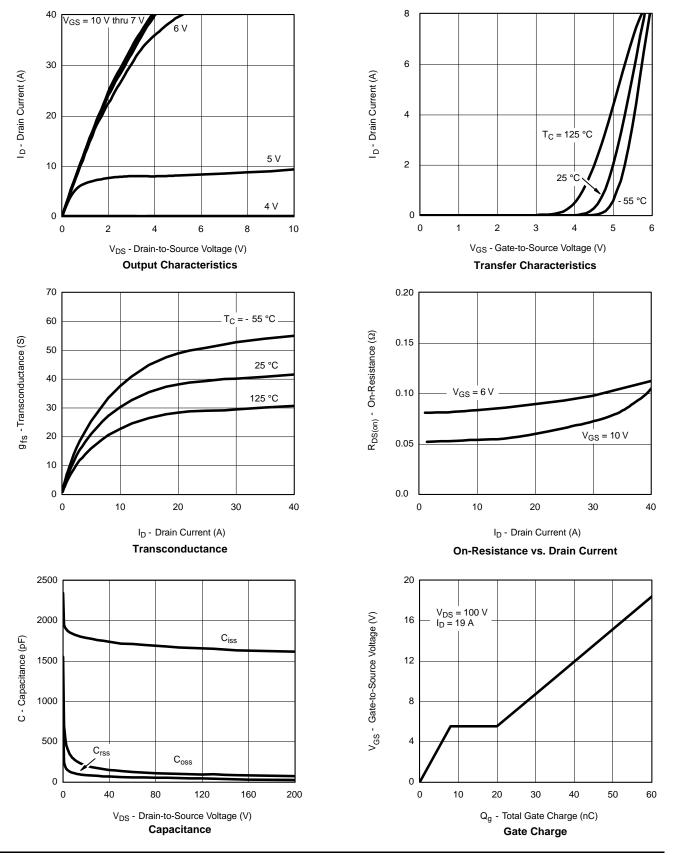
Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

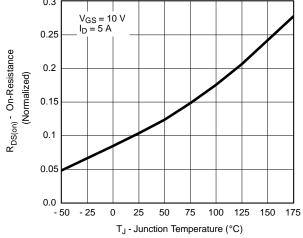


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

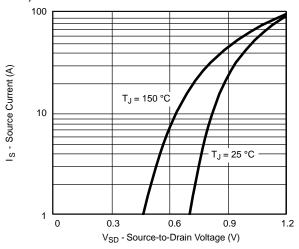




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





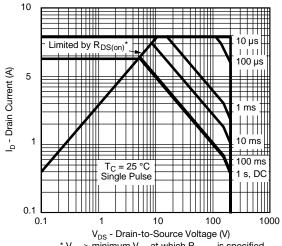


Source-Drain Diode Forward Voltage

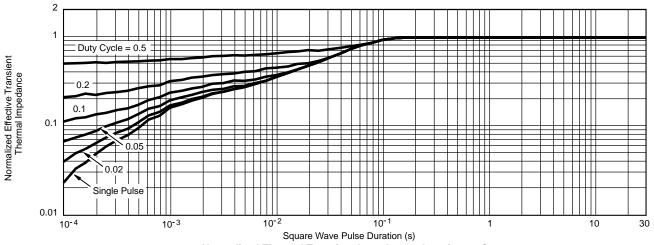
THERMAL RATINGS



Maximum Avalanche Drain Current vs. Case Temperature



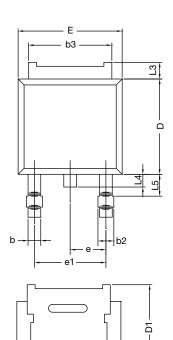
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified **Safe Operating Area**



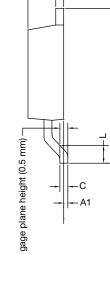
Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA CASE OUTLINE



E1



C2

	MILLIN	METERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090	BSC		
e1	4.56	4.56 BSC 0.180 BSC		BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: Y12-0247-Rev. M. 24-Dec-12						

ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

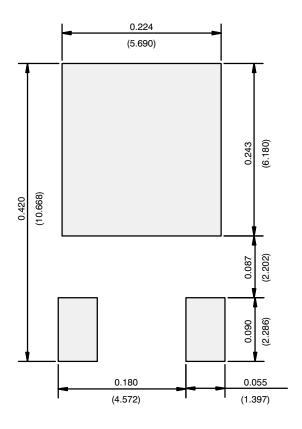
Note

• Dimension L3 is for reference only.

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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